BEST AVAILABLE COPY

U.S.S.N. 10/719,550

Claim Amendments

Please amend claims 1, 9, and 13 as follows: Please cancel claims 4, 6, 8, 16, 18, and 20 as follows: Please add new claims 21 - 25 as follows:

Claims as Amended

What is claimed is:

1. (currently amended) A process for removing oxidized metal residues from a metal structure, comprising the steps of:

providing a metal layer;

planarizing the metal layer to form a metal plug structure to leave metal residues on said metal plug structure;

providing an oxidant solution;

heating said exident solution to a temperature of at least about 60 degrees C; and

applying said exident solution to the metal plug structure to remove said metal residues comprising oxidized metal.

2. (original) The process of claim 1 wherein said oxidant

solution comprises hydroxylamine.

- 3. (original) The process of claim 1 wherein said applying said oxidant solution to the structure comprises spraying said oxidant solution onto the structure.
- 4. cancelled.
- 5. (original) The process of claim 1 wherein said heating said oxidant solution to a temperature of at least about 60 degrees C comprises heating said oxidant solution to a temperature of from about 60 degrees C to about 80 degrees C.
- 6. cancelled.
- 7. (original) The process of claim 5 wherein said applying said exident solution to the structure comprises spraying said exident solution onto the structure.
- 8. cancelled,
- 9. (currently amended) A process for removing tungsten residues from a tungsten plug structure, comprising the steps of:

providing a tungsten plug structure formed by a planarization process to form tungsten residues on said tungsten pluq structure;

providing an oxidant solution; and

applying said oxidant solution to the tungsten plug structure remove said tungsten cesidues comprising oxidized tungsten.

- 10. (original) The process of claim 9 wherein said oxidant solution comprises hydroxylamine.
- 11. (original) The process of claim 9 wherein said applying said oxidant solution to the structure comprises spraying said oxidant solution onto the structure.
- 12. (original) The process of claim 9 further comprising the step of heating said oxidant solution to a temperature of at least about 60 degrees C prior to said applying said oxidant solution to the tungsten plug structure.

13. (currently amended) A process for removing residues from a tungsten plug structure having at least one tungsten plug and a tungsten layer, comprising the steps of:

providing a tungsten layer overlying a dielectric layer to fill an opening formed in the dielectric layer;

etching said tungsten layer in a tungsten etchback process without photoresist present from said tungsten plug structure to form a tungsten plug structure comprising tungsten residues on said tungsten plug structure;

providing an oxidant solution; and

removing the <u>tungsten</u> residues from the tungsten plug structure by applying said oxidant solution to the tungsten plug structure to remove said tungsten residues comprising exidized tungsten.

- (original) The process of claim 13 wherein said exidant solution comprises hydroxylamine.
- 15. (original) The process of claim 13 wherein said applying said

oxidant solution to the Lungsten plug structure comprises spraying said oxidant solution onto the tungsten plug structure.

16. cancelled

17. (original) The process of claim 13 further comprising the step of heating said exident solution to a temperature of at least about 60 degrees C prior to said applying said exident solution to the tungsten plug structure.

18. cancelled

19. (original) The process of claim 17 wherein said applying said oxidant solution to the tungsten plug structure comprises spraying said oxidant solution onto the tungsten plug structure.

20. cancelled

- 21. (new) The process of claim 2, wherein the oxidant solution further comprises at least one alkanolamine.
- 22. (new) The process of claim 21, wherein the oxidant solution further comprises catechol.

- 23. (new) The process of claim 22, wherein the exidant solution further comprises dyglycolamine and gallic acid.
- 24. (new) The process of claim 14, wherein the oxidant solution further comprises, one or more alkanolamines, and catechol.
- 25. (new) The process of claim 13, wherein said tungston etchback process comprises a first tungsten etching step at a first etching rate followed by a second tungsten etching step at a second etching rate less than the first etching rate to expose an underlying barrier layer.

This Page is Inserted by IFW Indexing and Scanning Operations and is not part of the Official Record

BEST AVAILABLE IMAGES

Defective images within this document are accurate representations of the original documents submitted by the applicant.

Defects in the images include but are not limited to the items checked:

□ BLACK BORDERS
□ IMAGE CUT OFF AT TOP, BOTTOM OR SIDES
□ FADED TEXT OR DRAWING
□ BLURRED OR ILLEGIBLE TEXT OR DRAWING
□ SKEWED/SLANTED IMAGES
□ COLOR OR BLACK AND WHITE PHOTOGRAPHS
□ GRAY SCALE DOCUMENTS
□ LINES OR MARKS ON ORIGINAL DOCUMENT
□ REFERENCE(S) OR EXHIBIT(S) SUBMITTED ARE POOR QUALITY

IMAGES ARE BEST AVAILABLE COPY.

□ OTHER:

As rescanning these documents will not correct the image problems checked, please do not report these problems to the IFW Image Problem Mailbox.